

## N-Channel Enhancement-Mode Vertical DMOS FET

### Features

- Free from Secondary Breakdown
- Low Power Drive Requirement
- Ease of Paralleling
- Low  $C_{ISS}$  and Fast Switching Speeds
- Excellent Thermal Stability
- Integral Source-drain Diode
- High Input Impedance and High Gain

### Applications

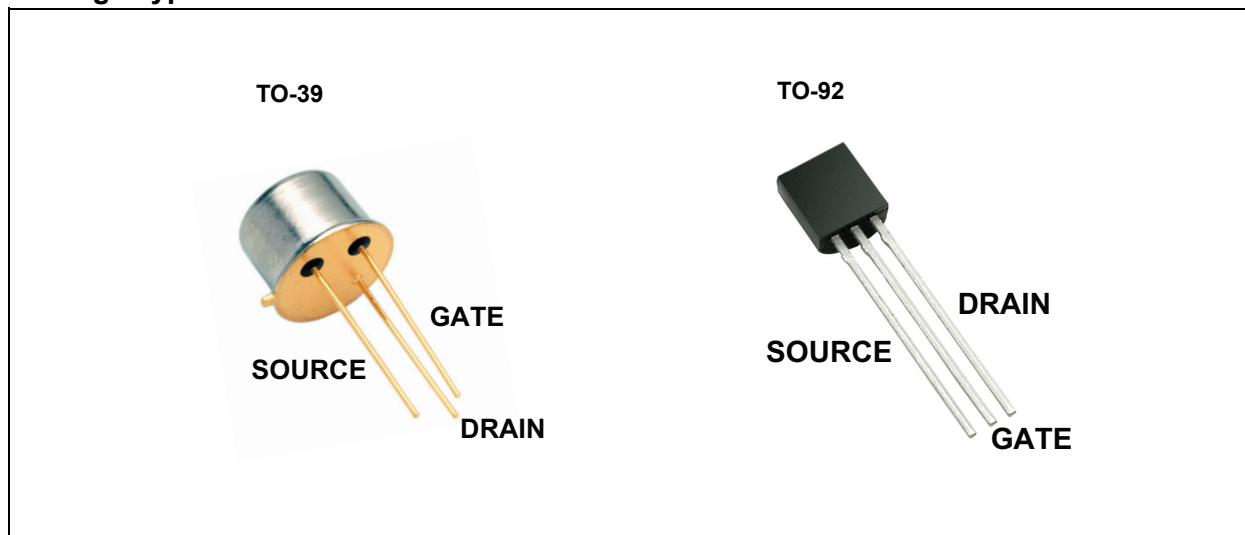
- Motor Controls
- Converters
- Amplifiers
- Switches
- Power Supply Circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memory, Displays, Bipolar Transistors, etc.)

### General Description

VN2210 is an Enhancement-mode (normally-off) transistor that utilizes a vertical Double-diffused Metal-Oxide Semiconductor (DMOS) structure and a well-proven silicon gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors as well as the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Vertical DMOS Field-Effect Transistors (FETs) are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance and fast switching speeds are desired.

### Package Types



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

|                                          |                                   |
|------------------------------------------|-----------------------------------|
| Drain-to-source Voltage .....            | $BV_{DSS}$                        |
| Drain-to-gate Voltage .....              | $BV_{DGS}$                        |
| Gate-to-source Voltage .....             | $\pm 20V$                         |
| Operating and Storage Temperatures ..... | $-55^{\circ}C$ to $+150^{\circ}C$ |

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

## ELECTRICAL CHARACTERISTICS

| Electrical Specifications: T <sub>A</sub> = 25°C unless otherwise specified. |                      |      |      |      |       |                                                                                             |
|------------------------------------------------------------------------------|----------------------|------|------|------|-------|---------------------------------------------------------------------------------------------|
| Parameters                                                                   | Sym.                 | Min. | Typ. | Max. | Units | Conditions                                                                                  |
| DC PARAMETERS (Note 1 unless otherwise specified)                            |                      |      |      |      |       |                                                                                             |
| Drain-to-source Breakdown Voltage                                            | BV <sub>DSS</sub>    | 100  | —    | —    | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 10 mA                                                |
| Gate Threshold Voltage                                                       | V <sub>GS(th)</sub>  | 0.8  | —    | 2.4  | V     | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 10 mA                                  |
| Change in V <sub>GS(th)</sub> with Temperature                               | ΔV <sub>GS(th)</sub> | —    | −4.3 | −5.5 | mV/°C | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 10 mA (Note 2)                         |
| Gate Body Leakage Current                                                    | I <sub>GSS</sub>     | —    | —    | 100  | nA    | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V                                                |
| Zero Gate Voltage Drain Current                                              | I <sub>DSS</sub>     | —    | —    | 50   | μA    | V <sub>GS</sub> = 0V, V <sub>DS</sub> = Maximum rating                                      |
|                                                                              |                      | —    | —    | 10   | mA    | V <sub>DS</sub> = 0.8 maximum rating, V <sub>GS</sub> = 0V, T <sub>A</sub> = 125°C (Note 2) |
| ON-State Drain Current                                                       | I <sub>D(ON)</sub>   | 3    | 4.5  | —    | A     | V <sub>GS</sub> = 5V, V <sub>DS</sub> = 25V                                                 |
|                                                                              |                      | 8    | 17   | —    |       | V <sub>GS</sub> = 10V, V <sub>DS</sub> = 25V                                                |
| Static Drain-to-source ON-State Resistance                                   | R <sub>DS(ON)</sub>  | —    | 0.4  | 0.5  | Ω     | V <sub>GS</sub> = 5V, I <sub>D</sub> = 1A                                                   |
|                                                                              |                      | —    | 0.27 | 0.35 |       | V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A                                                  |
| Change in R <sub>DS(ON)</sub> with Temperature                               | ΔR <sub>DS(ON)</sub> | —    | 0.85 | 1.2  | %/°C  | V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A (Note 2)                                         |
| AC PARAMETERS (Note 2)                                                       |                      |      |      |      |       |                                                                                             |
| Forward Transconductance                                                     | G <sub>FS</sub>      | 1200 | —    | —    | mmho  | V <sub>DS</sub> = 25V, I <sub>D</sub> = 2A                                                  |
| Input Capacitance                                                            | C <sub>ISS</sub>     | —    | 300  | 500  | pF    | V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1 MHz                                      |
| Common Source Output Capacitance                                             | C <sub>OSS</sub>     | —    | 125  | 200  |       |                                                                                             |
| Reverse Transfer Capacitance                                                 | C <sub>RSS</sub>     | —    | 50   | 65   | ns    | V <sub>DD</sub> = 25V, I <sub>D</sub> = 2A, R <sub>GEN</sub> = 10Ω                          |
| Turn-on Time                                                                 | t <sub>d(ON)</sub>   | —    | 10   | 15   |       |                                                                                             |
| Rise Time                                                                    | t <sub>r</sub>       | —    | 10   | 15   |       |                                                                                             |
| Turn-off Time                                                                | t <sub>d(OFF)</sub>  | —    | 50   | 65   |       |                                                                                             |
| Fall Time                                                                    | t <sub>f</sub>       | —    | 30   | 50   |       |                                                                                             |
| DIODE PARAMETERS                                                             |                      |      |      |      |       |                                                                                             |
| Diode Forward Voltage Drop                                                   | V <sub>SD</sub>      | —    | 1    | 1.6  | V     | V <sub>GS</sub> = 0V, I <sub>SD</sub> = 4A (Note 1)                                         |
| Reverse Recovery Time                                                        | t <sub>rr</sub>      | —    | 500  | —    | ns    | V <sub>GS</sub> = 0V, I <sub>SD</sub> = 1A (Note 2)                                         |

**Note 1:** All DC parameters are 100% tested at  $25^{\circ}C$  unless otherwise stated.  
(Pulse test: 300  $\mu s$  pulse, 2% duty cycle)

**2:** Specification is obtained by characterization and is not 100% tested.

## TEMPERATURE SPECIFICATIONS

| <b>Electrical Characteristics:</b> Unless otherwise specified, for all specifications $T_A = T_J = +25^{\circ}\text{C}$ . |               |      |      |      |                      |            |
|---------------------------------------------------------------------------------------------------------------------------|---------------|------|------|------|----------------------|------------|
| Parameters                                                                                                                | Sym.          | Min. | Typ. | Max. | Units                | Conditions |
| <b>TEMPERATURE RANGES</b>                                                                                                 |               |      |      |      |                      |            |
| Operating Temperature                                                                                                     | $T_A$         | -55  | —    | +150 | $^{\circ}\text{C}$   |            |
| Storage Temperature                                                                                                       | $T_S$         | -55  | —    | +150 | $^{\circ}\text{C}$   |            |
| <b>PACKAGE THERMAL RESISTANCES</b>                                                                                        |               |      |      |      |                      |            |
| TO-39                                                                                                                     | $\theta_{JA}$ | —    | N/A  | —    | —                    |            |
| TO-92                                                                                                                     | $\theta_{JA}$ | —    | 132  | —    | $^{\circ}\text{C/W}$ |            |

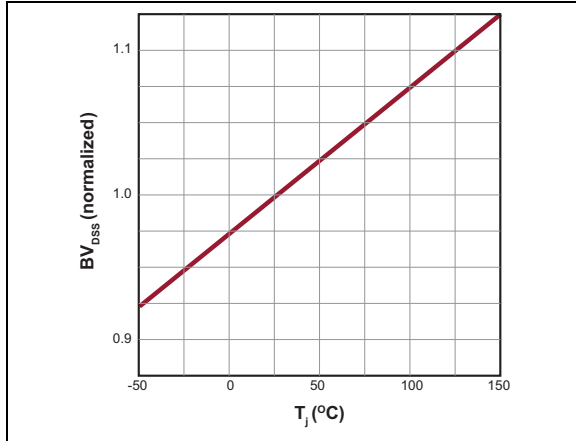
## THERMAL CHARACTERISTICS

| Package | $I_D$ (Note 1)<br>(Continuous)<br>(A) | $I_D$<br>(Pulsed)<br>(A) | Power Dissipation at<br>$T_C = 25^{\circ}\text{C}$<br>(W) | $I_{DR}$ (Note 1)<br>(A) | $I_{DRM}$<br>(A) |
|---------|---------------------------------------|--------------------------|-----------------------------------------------------------|--------------------------|------------------|
| TO-39   | 1.7                                   | 10                       | 0.36                                                      | 1.7                      | 10               |
| TO-92   | 1.2                                   | 8                        | 0.74                                                      | 1.2                      | 8                |

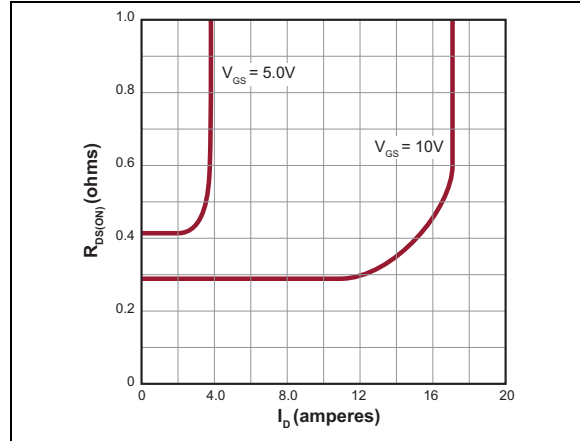
**Note 1:**  $I_D$  (continuous) is limited by maximum  $T_J$ .

## 2.0 TYPICAL PERFORMANCE CURVES

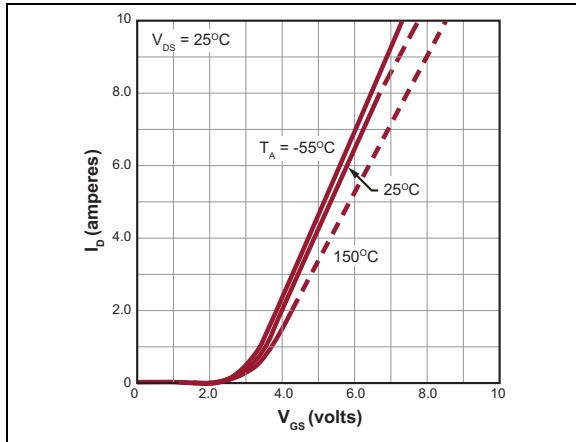
**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.



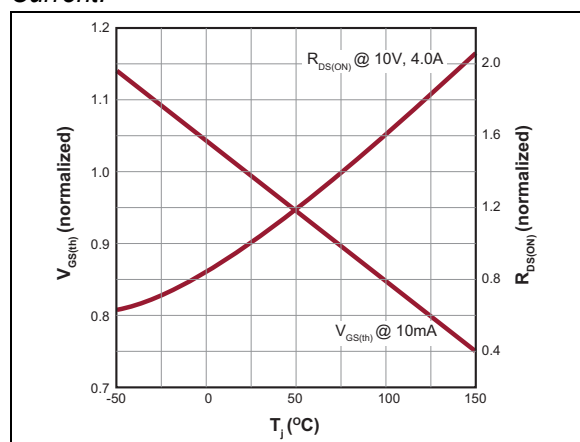
**FIGURE 2-1:**  $BV_{DSS}$  Variation with Temperature.



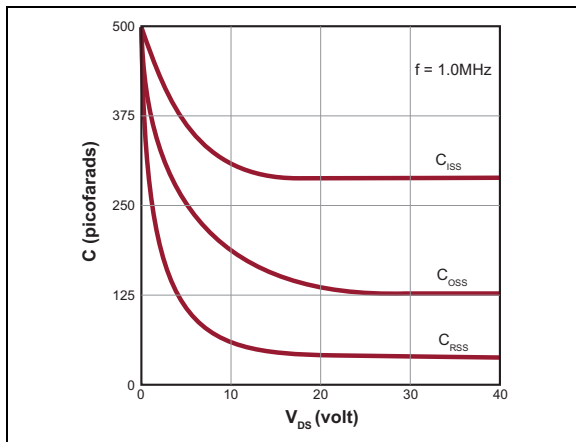
**FIGURE 2-4:** On-resistance vs. Drain Current.



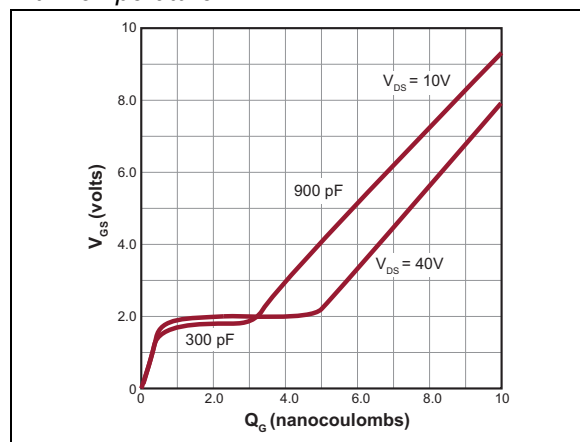
**FIGURE 2-2:** Transfer Characteristics.



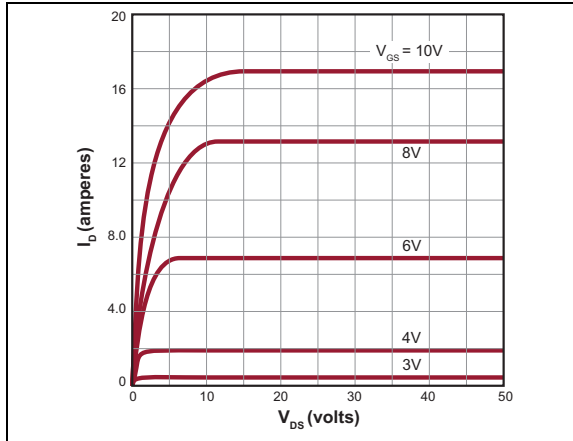
**FIGURE 2-5:**  $V_{GS}$  and  $R_{DS(on)}$  Variation with Temperature.



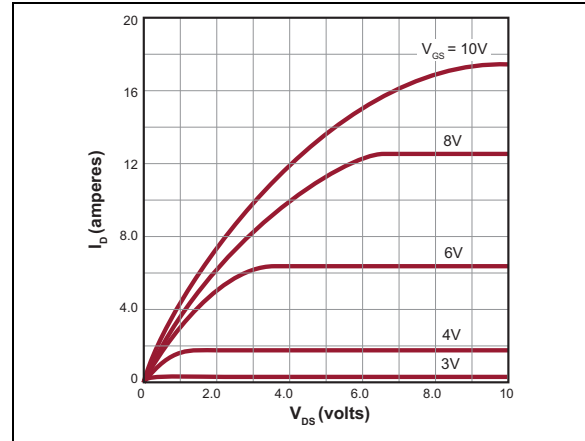
**FIGURE 2-3:** Capacitance vs. Drain-to-source Voltage.



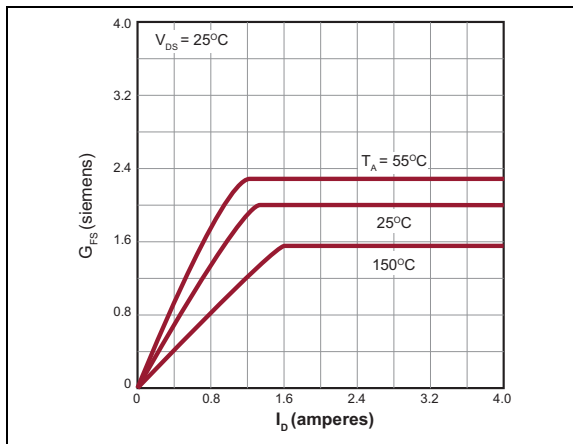
**FIGURE 2-6:** Gate Drive Dynamic Characteristics.



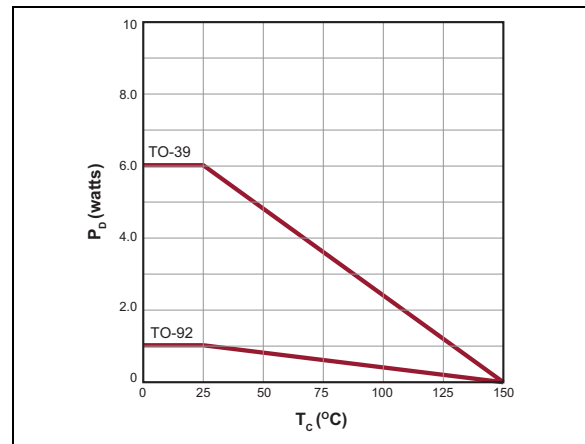
**FIGURE 2-7:** Output Characteristics.



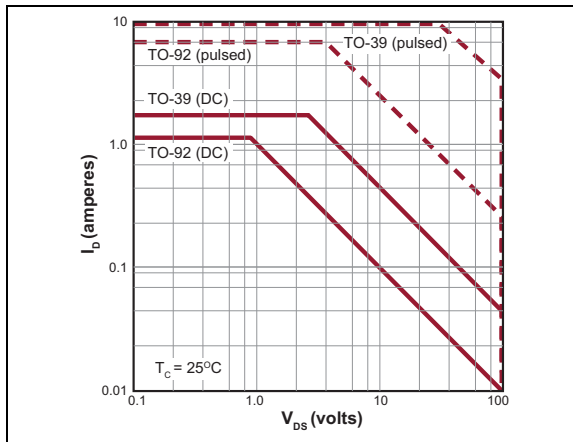
**FIGURE 2-10:** Saturation Characteristics.



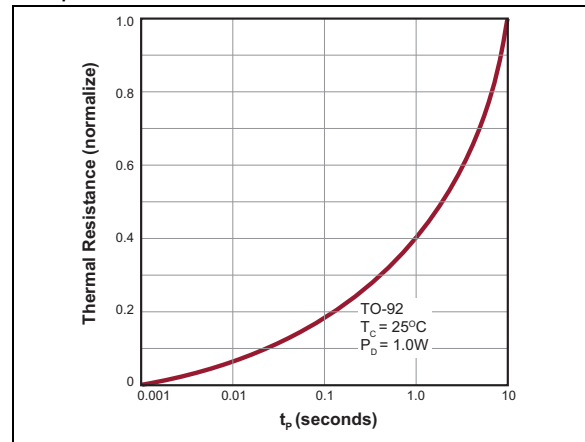
**FIGURE 2-8:** Transconductance vs. Drain Current.



**FIGURE 2-11:** Power Dissipation vs. Case Temperature.



**FIGURE 2-9:** Maximum Rated Safe Operating Area.



**FIGURE 2-12:** Thermal Response Characteristics.

## 3.0 PIN DESCRIPTION

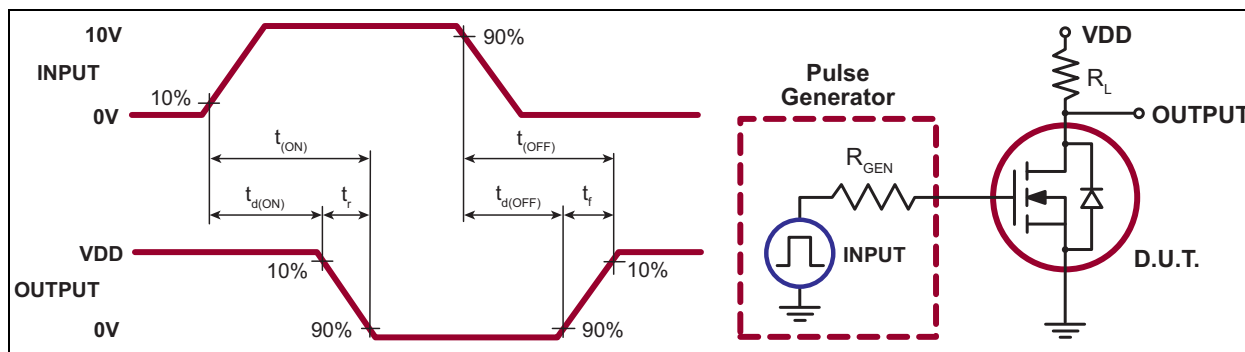
Table 3-1 shows the description of pins in TO-39 and TO-92.

**TABLE 3-1: TO-39/TO-92 PIN FUNCTION TABLE**

| Pin Number | TO-39  | TO-92  | Description |
|------------|--------|--------|-------------|
| 1          | Source | Source | Source      |
| 2          | Gate   | Gate   | Gate        |
| 3          | Drain  | Drain  | Drain       |

## 4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for VN2210.



**FIGURE 4-1:** Switching Waveforms and Test Circuit.

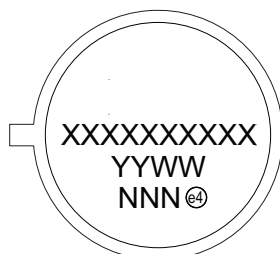
## PRODUCT SUMMARY

| $BV_{DSS}/BV_{DGS}$<br>(V) | $R_{DS(ON)}$<br>(Maximum)<br>( $\Omega$ ) | $V_{GS(th)}$<br>(Maximum)<br>(V) |
|----------------------------|-------------------------------------------|----------------------------------|
| 100                        | 0.35                                      | 2.4                              |

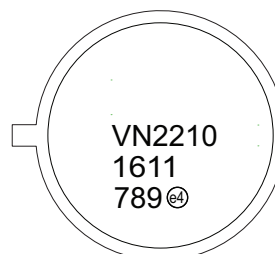
## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

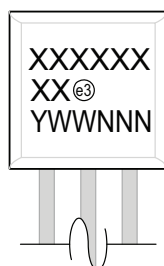
3-Lead TO-39



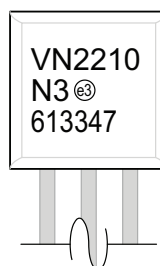
Example



3-lead TO-92



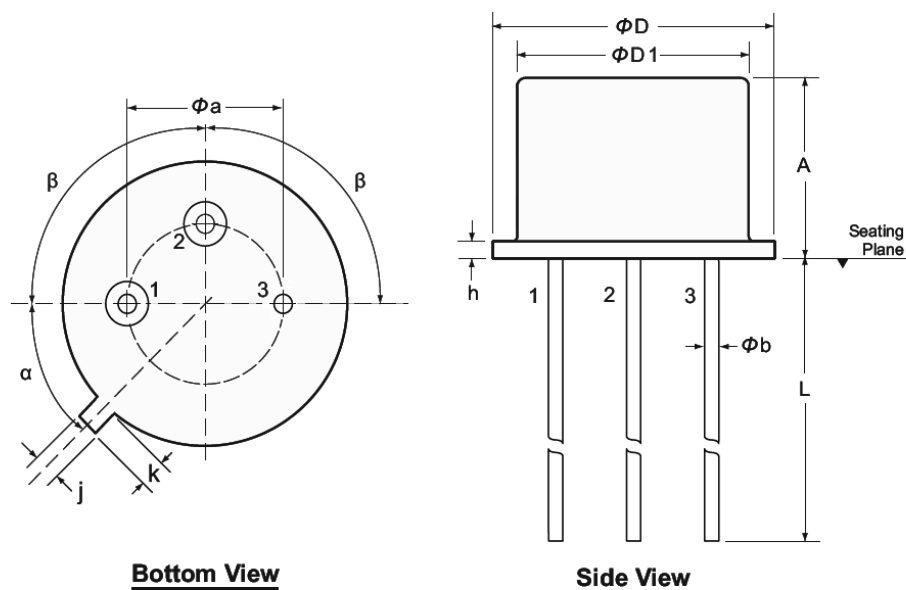
Example



|                |        |                                                                                                                  |
|----------------|--------|------------------------------------------------------------------------------------------------------------------|
| <b>Legend:</b> | XX...X | Product Code or Customer-specific information                                                                    |
|                | Y      | Year code (last digit of calendar year)                                                                          |
|                | YY     | Year code (last 2 digits of calendar year)                                                                       |
|                | WW     | Week code (week of January 1 is week '01')                                                                       |
|                | NNN    | Alphanumeric traceability code                                                                                   |
|                | (e3)   | Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn)                                                         |
|                | *      | This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. |
|                | (e4)   | Pre-plated                                                                                                       |

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

## 3-Lead TO-39 Package Outline (N2)



Note: For the most current package drawings, see the Microchip Packaging Specification at [www.microchip.com/packaging](http://www.microchip.com/packaging).

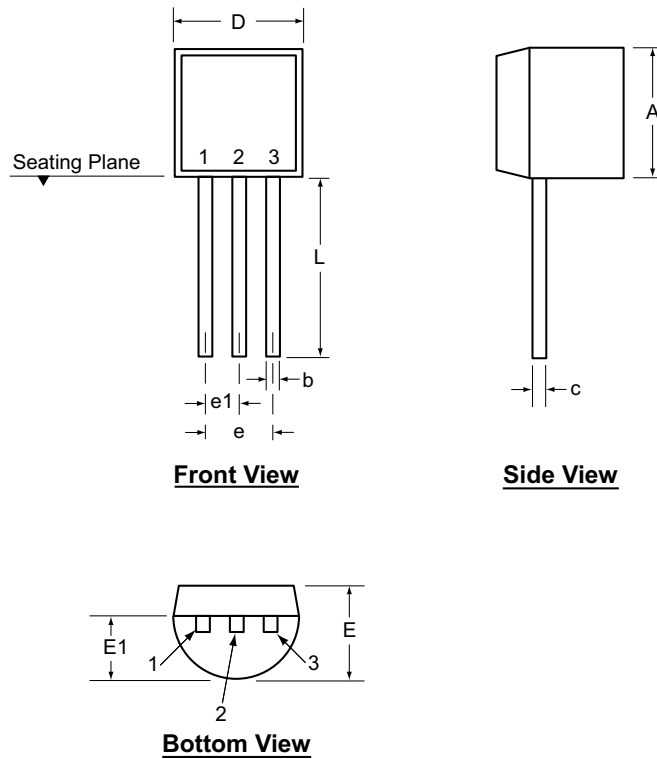
| Symbol                |     | $\alpha$   | $\beta$    | A    | $\phi a$ | $\phi b$ | $\phi D$ | $\phi D1$ | h    | j    | k    | L     |
|-----------------------|-----|------------|------------|------|----------|----------|----------|-----------|------|------|------|-------|
| Dimension<br>(inches) | MIN | 45°<br>NOM | 90°<br>NOM | .240 | .190     | .016     | .350     | .315      | .009 | .028 | .029 | .500  |
|                       | NOM |            |            | -    | -        | -        | -        | -         | -    | -    | -    | -     |
|                       | MAX |            |            | .260 | .210     | .021     | .370     | .335      | .125 | .034 | .040 | .560* |

JEDEC Registration TO-39.

\* This dimension is not specified in the JEDEC drawing.

Drawings not to scale.

## 3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at [www.microchip.com/packaging](http://www.microchip.com/packaging).

| Symbol                 |     | A    | b                 | c                 | D    | E    | E1   | e    | e1   | L     |
|------------------------|-----|------|-------------------|-------------------|------|------|------|------|------|-------|
| Dimensions<br>(inches) | MIN | .170 | .014 <sup>†</sup> | .014 <sup>†</sup> | .175 | .125 | .080 | .095 | .045 | .500  |
|                        | NOM | -    | -                 | -                 | -    | -    | -    | -    | -    | -     |
|                        | MAX | .210 | .022 <sup>†</sup> | .022 <sup>†</sup> | .205 | .165 | .105 | .105 | .055 | .610* |

JEDEC Registration TO-92.

\* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

**Drawings not to scale.**

## APPENDIX A: REVISION HISTORY

### Revision A (June 2016)

- Converted Supertex Doc# DSFP-VN2210 to Microchip DS20005559A.
- Made minor text changes throughout the document.

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

| <u>PART NO.</u>                                                                                       |                 | <u>XX</u> | -                                                 | <u>X</u>      | - | <u>X</u>   |
|-------------------------------------------------------------------------------------------------------|-----------------|-----------|---------------------------------------------------|---------------|---|------------|
| Device                                                                                                | Package Options |           |                                                   | Environmental |   | Media Type |
| Device:                                                                                               | VN2210          | =         | N-Channel Enhancement-Mode Vertical DMOS FET      |               |   |            |
| Packages:                                                                                             | N2              | =         | 3-lead TO-39                                      |               |   |            |
|                                                                                                       | N3              | =         | 3-lead TO-92                                      |               |   |            |
| Environmental:                                                                                        | G               | =         | Lead (Pb)-free/RoHS-compliant Package             |               |   |            |
| Media Type:                                                                                           | (blank)         | =         | 500/Bag for N2 Package<br>1000/Bag for N3 Package |               |   |            |
| Note: VN2210N2 does not include a “-G” designator. However, the package is an RoHS-compliant product. |                 |           |                                                   |               |   |            |

|                  |                                                                                    |
|------------------|------------------------------------------------------------------------------------|
| <b>Examples:</b> |                                                                                    |
| a) VN2210N2:     | N-Channel Enhancement-Mode<br>Vertical DMOS FET, 3-lead TO-39<br>Package, 500/Bag  |
| b) VN2210N3-G:   | N-Channel Enhancement-Mode<br>Vertical DMOS FET, 3-lead TO-92<br>Package, 1000/Bag |

### Examples:

- a) VN2210N2: N-Channel Enhancement-Mode Vertical DMOS FET, 3-lead TO-39 Package, 500/Bag
- b) VN2210N3-G: N-Channel Enhancement-Mode Vertical DMOS FET, 3-lead TO-92 Package, 1000/Bag

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

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